

A5-Sub B2
6. (Twice Amended) The composition according to claim 1, wherein a total content of the N-methyl-2-pyrrolidone and ethylene glycol monobutyl ether is 80 to 90 wt%, and a ratio of a content of the N-methyl-2-pyrrolidone to the total content of the N-methyl-2-pyrrolidone and ethylene glycol monobutyl ether is 0.75 to 0.95.

Sub C1
A6
7. (Amended) A cleaning method for removing a byproduct derived from a decomposed substance of a process gas containing C and F, and deposited on a component in a process chamber of a semiconductor processing apparatus for subjecting a target substrate to a semiconductor process with the process gas,

the method comprising:

removing the component from the process chamber; and

dipping the component in a bath of a cleaning solution comprising N-methyl-2-pyrrolidone, ethylene glycol monobutyl ether, a surfactant, and water.

8. (Amended) The cleaning method according to claim 7, wherein the component is dipped in the bath of the cleaning solution while the component is stored in a cage with 500 to 100 meshes.

A7
9. (Twice Amended) The cleaning method according to claim 7, wherein the component is dipped in the bath of the cleaning solution while a temperature of the cleaning solution is set at 50 to 80°C.

10. (Twice Amended) The cleaning method according to claim 7, wherein the semiconductor process comprises etching a layer consisting essentially of a silicon oxide on the target substrate by using the process gas.

11. (Twice Amended) The cleaning method according to claim 7, wherein the cleaning solution further contains an alkali metal concentration of less than 10 ppb.

12. (Twice Amended) The cleaning method according to claim 7, wherein, in the cleaning solution, a total content of the N-methyl-2-pyrrolidone and ethylene glycol monobutyl ether is 80 to 90 wt%, and a ratio of a content of the N-methyl-2-pyrrolidone to

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Control
Sub 1
the total content of the N-methyl-2-pyrrolidone and ethylene glycol monobutyl ether is 0.75 to 0.95.

Please add the following new claims:

AS
✓ 13. (New) A composition comprising N-methyl-2-pyrrolidone, ethylene glycol monobutyl ether, and a surfactant, -EP

wherein the surfactant concentration is 0.1 to 1.0 wt%.

✓ 14. (New) The composition according to claim 13, further comprising water.

✓ 15. (New) The composition according to claim 14, wherein the water concentration is 5 to 20 wt%.

✓ 16. (New) The composition according to claim 13, wherein the surfactant contains fluorine. two reject.

✓ 17. (New) The composition according to claim 13, wherein a total content of the N-methyl-2-pyrrolidone and ethylene glycol monobutyl ether is 80 to 90 wt%, and a ratio of a content of the N-methyl-2-pyrrolidone to the total content of the N-methyl-2-pyrrolidone and ethylene glycol monobutyl ether is 0.75 to 0.95.

✓ 18. (New) The composition according to claim 13, wherein the composition comprises 10 ppb or less of an alkali metal. -EP.

Sub B3
✓ 19. (New) The composition according to claim 1, wherein the composition comprises 10 ppb or less of an alkali metal.

Sub C
✓ 20. (New) The cleaning method according to claim 7, wherein the water concentration is 5 to 20 wt%.

✓ 21. (New) The cleaning method according to claim 7, wherein the surfactant concentration is 0.1 to 1.0 wt%.

BASIS FOR THE AMENDMENT

Claim 2 has been cancelled.

Claims 1 and 3-12 have been amended.

Claims 13-21 have been added.

The amendment of Claim 1 is supported by Claim 2. The amendments of Claims 3-6 and 8-12 are supported by the original claims as filed. The amendment of Claim 7 is supported by page 12, lines 21-23. New Claims 13-18 are supported by Claims 1-6. New Claim 19 is supported by original Claim 1. New Claims 20 are supported by page 12, lines 21-23. New Claim 21 is supported by page 6, lines 4-7. In addition, consistent with the Examiner's objection under 37 C.F.R. §1.126 and subsequent correction, Applicants have renumbered Claims 3-13 as Claims 2-12 herein for sake of clarity.

No new matter is believed to have been added by these amendments.